



Date: 03 December 2025

Federal Communications Commission

Authorization and Evaluation Division

7435 Oakland Mills Road

Columbia, MD 21046

USA

Ref: Modular Approval Letter for Host Device Model KR210-K

Host FCC ID: 2ALZSKR210WMAE

Integrated Module FCC ID: QOQ-GM240P (Silicon Labs BGM240PB22VNA3)

To Whom It May Concern:

This letter confirms that the Bluetooth Low Energy module **BGM240PB22VNA3**, certified under **FCC ID QOQ-GM240P**, has been integrated into the host device **KR210-K (FCC ID 2ALZSKR210WMAE)** in full accordance with the module manufacturer's integration instructions and all grant restrictions associated with the module's certification.

The module has been installed exactly as specified by Silicon Labs, including required PCB layout guidelines, antenna configuration, separation distances, and operational parameters. The host device does **not** modify, alter, or reconfigure the module hardware, RF paths, or antenna in any way. No RF bands, modulation capabilities, or operational modes have been disabled or changed. The module operates solely under its original certified configuration.

The module incorporated is the **BGM240PB22VNA3**, corresponding to the grant **FCC ID QOQ-GM240P**, originally certified on its grant date as published in the FCC database.

We confirm that the KR210-K maintains compliance with all relevant FCC requirements for modular integration, including RF exposure, labeling, emissions, and operational restrictions.

Sincerely,

Jaimie Crafton

Senior Systems Engineer